# **Axial Lead Rectifier**

... employing the Schottky Barrier principle in a large area metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlap contact. Ideally suited for use as rectifiers in low-voltage, high-frequency inverters, free wheeling diodes, and polarity protection diodes.

- Extremely Low V<sub>f</sub>
- Low Power Loss/High Efficiency
- Highly Stable Oxide Passivated Junction
- Low Stored Charge, Majority Carrier Conduction

#### **Mechanical Characteristics:**

- Case: Epoxy, Molded
- Weight: 0.4 gram (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 220°C Max. for 10 Seconds, 1/16" from case
- Available Tape and Reeled, 5000 per reel, by adding a "RL" suffix to the part number
- Polarity: Cathode indicated by Polarity Band
- ESD Ratings: Machine Model = A
  - Human Body Model = 2
- Marking: MBR3060

## **MAXIMUM RATINGS**

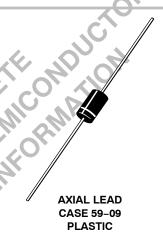
Rating	Symbol	Max	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>r</sub>	60	<b>V</b>
Average Rectified Forward Current $T_L = 125^{\circ}C$ ( $R_{\theta JL} = 13^{\circ}C/W$ , P.C. Board Mounting)	lo	3.0	A
Non-Repetitive Peak Surge Current	I <sub>FSM</sub>	125	Α
Operating and Storage Junction Temperature Range (Reverse Voltage Applied)	T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	°C
Peak Operating Junction Temperature (Forward Current Applied)	T <sub>J(pk)</sub>	150	°C



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SCHOTTKY BARRIER RECTIFIER 3.0 AMPERES **60 VOLTS** 



#### **MARKING DIAGRAM**



MBR3060 = Device Code

## **ORDERING INFORMATION**

Device Package		Shipping	
MBR3060	Axial Lead	1000 Units/Bag	
MBR3060RL	Axial Lead	5000/Tape & Reel	

#### THERMAL CHARACTERISTICS

Characteristic		Max	Unit
Thermal Resistance, Junction-to-Lead (Note 1, see Note 3, Mounting Method 3)	$R_{\theta JL}$	13	°C/W
Thermal Resistance, Junction-to-Ambient (see Note 3, Mounting Method 3)	$R_{\theta JA}$	50	°C/W

## **ELECTRICAL CHARACTERISTICS** (T<sub>L</sub> = 25°C unless otherwise noted) (Note 1)

Characteristic	Symbol	Max	Unit
Maximum Instantaneous Forward Voltage (Note 2) $ \begin{aligned} &(I_f=3.0 \text{ Amp}), \ T_L=25^{\circ}\text{C} \\ &(I_f=3.0 \text{ Amp}), \ T_L=100^{\circ}\text{C} \end{aligned} $	V <sub>f</sub>	0.62 0.59	V
Maximum Instantaneous Reverse Current (Note 2) $(V_r = 60 \text{ V}), T_L = 25^{\circ}\text{C}$ $(V_r = 60 \text{ V}), T_L = 100^{\circ}\text{C}$	I <sub>r</sub>	150 10	μA mA

<sup>1.</sup> Lead Temperature reference is cathode lead at printed wiring board.

# TYPICAL CHARACTERISTICS

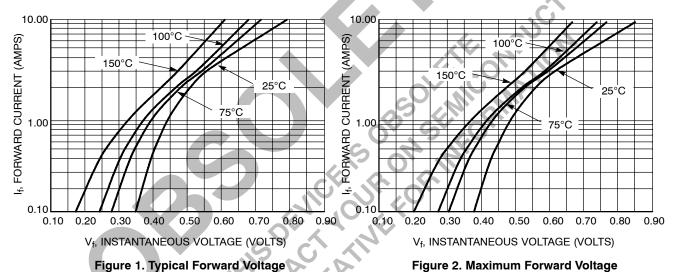


Figure 1. Typical Forward Voltage

150°C

100°C

75°C

25°C

1000 f = 1 MhzC, CAPACITANCE (pF) 25°C 100 10 60 50 60 V<sub>r</sub>, REVERSE VOLTAGE (VOLTS)

V<sub>r</sub>, REVERSE VOLTAGE (VOLTS) Figure 3. Typical Reverse Current

Figure 4. Typical Capacitance

50

10

100

1.0

0.1

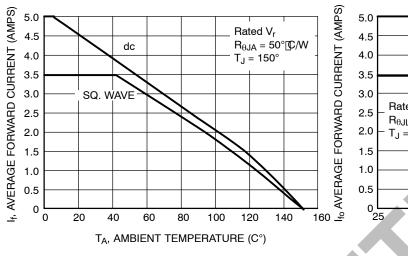
0.001

0.0001

I, REVERSE CURRENT (mA)

<sup>2.</sup> Pulse Test: Pulse Width = 300 μs, Duty Cycle = 2.0%.

#### **TYPICAL CHARACTERISTICS**

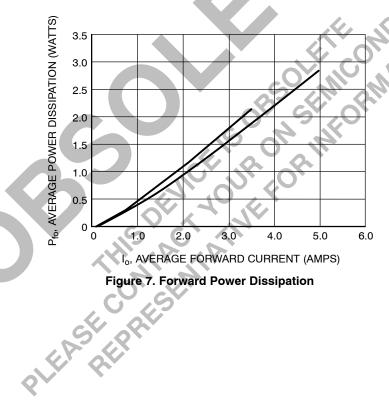


Rated V<sub>r</sub> SQ. WAVE  $R_{\theta JL} = 13^{\circ} \text{C/W}$  $T_{J} = 150^{\circ}$ 85 65 125 145 165 T<sub>I</sub>, LEAD TEMPERATURE (C°)

dc -

Figure 5. Current Derating - Ambient

Figure 6. Current Derating - Lead



## **NOTE 3 — MOUNTING DATA**

Data shown for thermal resistance junction—to—ambient  $(R_{\theta JA})$  and thermal resistance junction—to—lead  $(R_{\theta JL})$  for the mountings shown is to be used as typical guideline values for preliminary engineering, or in case the tie point temperature cannot be measured.

TYPICAL VALUES FOR  $R_{\theta JA}$  IN STILL AIR

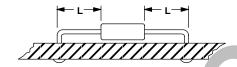
Mounting	Lead Length, L (in)				
Method	1/8	1/4	1/2	3/4	$R_{\theta JA}$
1	52	65	72	85	°C/W
2	67	80	87	100	°C/W
3	50			°C/W	

TYPICAL VALUES FOR  $R_{\theta JL}$  IN STILL AIR

Mounting	Lead Length, L (in)			
Method	1/8	1/4	1/2	$R_{\theta JA}$
1	15	23	37	°C/W
2	30	38	52	°C/W
3		13		°C/W

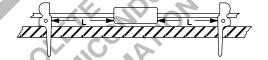
## **Mounting Method 1**

P.C. Board with  $1-1/2'' \times 1-1/2''$  copper surface.



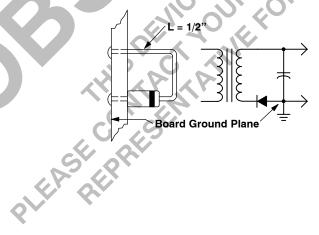
## Mounting Method 2

Vector Push-In Terminals T-28



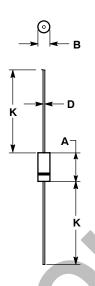
## Mounting Method 3

P.C. Board with 1–1/2″ X 1–1/2″ ©opper surface.



## PACKAGE DIMENSIONS

# **AXIAL LEAD** CASE 59-09 **ISSUE R**



NOTES

- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- 59-04 OBSOLETE, NEW STANDARD 59-09. 59-03 OBSOLETE, NEW STANDARD 59-10.
- ALL RULES AND NOTES ASSOCIATED WITH JEDEC DO-41 OUTLINE SHALL APPLY.
- POLARITY DENOTED BY CATHODE BAND.
  LEAD DIAMETER NOT CONTROLLED WITHIN F

4	INCHES		MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.228	0.299	5.80	7.60
В	0.102	0.142	2.60	3.60
D	0.028	0.034	0.71	0.86
K	1.000		25.44	

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